

SEMITOP® 2 Press-Fit

Two separated thyristors

SK100TAA16p

Features*

- · Compact design
- One screw mounting
- Solder free mounting with Press-Fit terminals
- High current density due to double mesa technology
- Heat transfer and insulation through direct copper bonded aluminum oxide ceramic (DBC)
- Glass passivated thyristor chips
- Up to 1600V reverse voltage
- High surge currents
- UL recognized, file no. E 63 532

Typical Applications

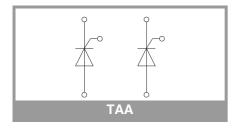
- · Controlled rectifier circuit
- Solid state relays

Absolute Maximum Ratings					
Symbol	Conditions	Values			
Thyristor 1					
V_{RRM}		1600	V		
V_{DRM}		1600	V		
I _{T(AV)}	T _j = 130 °C, T _s = 70 °C	93	Α		
I _{TSM}	$t_p = 10 \text{ ms, sin } 180^{\circ}, T_j = 25 ^{\circ}\text{C}$	2000	Α		
i ² t	$t_p = 10 \text{ ms, sin } 180^{\circ}, T_j = 25 ^{\circ}\text{C}$	20000	A ² s		
Tj		-40 130	°C		

Absolute Maximum Ratings				
Symbol	Conditions	Values U		
Module				
I _{t(RMS)}	ΔT _{terminal} at PCB joint = 30 K, per pin	35	Α	
T _{stg}	module without TIM	-40 125	°C	
V _{isol}	AC, sinusoidal, t = 1 min	2500	V	

Characteristics					
Symbol	Conditions	min.	typ.	max.	Unit
Thyristor	Thyristor 1				
V _T	T _j = 25 °C, I _T = 150 A			1.26	V
$V_{T(TO)}$	T _j = 130 °C			0.85	V
r _T	T _j = 130 °C			2.20	mΩ
I _{DD} ;I _{RD}	$T_j = 130 ^{\circ}\text{C}, V_{DD} = V_{DRM}; V_{RD} = V_{RRM}$			21	mA
t _{gd}	$T_j = 25$ °C, $I_G = 1$ A, $di_G/dt = 1$ A/ μs		1		μs
t _{gr}	V _D = 0.67 * V _{DRM}		2		μs
tq	T _j = 130 °C		150		μs
I _H	T _j = 25 °C	220			mA
IL	$T_j = 25$ °C, $R_G = 33 \Omega$	550			mA
V_{GT}	$T_j = 25$ °C, d.c.	2			V
I _{GT}	$T_j = 25$ °C, d.c.	100			mA
V_{GD}	T _j = 130 °C, d.c.			0.25	V
I _{GD}	T _j = 130 °C, d.c.			6	mA
R _{th(j-s)}	per thyristor, λ_{paste} =0.8 W/(mK), sin. 180°		0.47		K/W

Characteristics					
Symbol	Conditions	min.	typ.	max.	Unit
Module					
Ms	to heatsink	1.8		2	Nm
W	weight		19		g



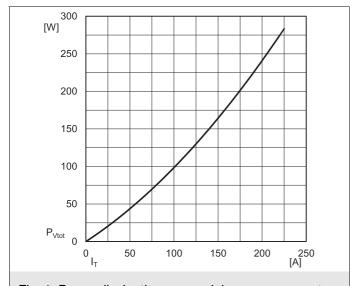
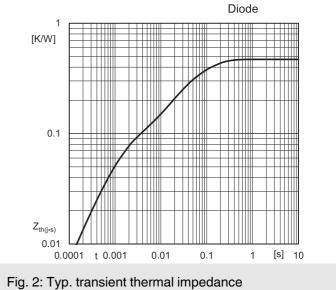


Fig. 1: Power dissipation per module vs. rms current



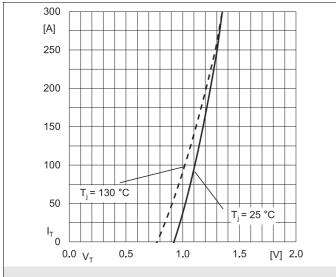


Fig. 3: Typ. forward characteristic of single thyristor

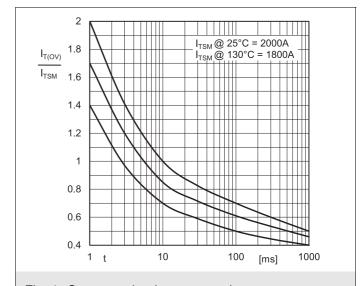


Fig. 4: Surge overload current vs. time

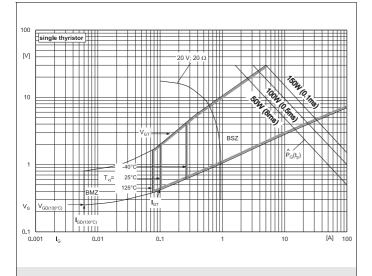
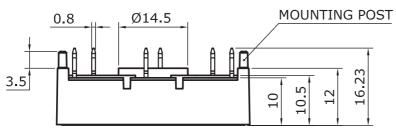
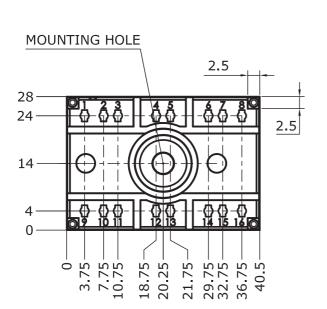


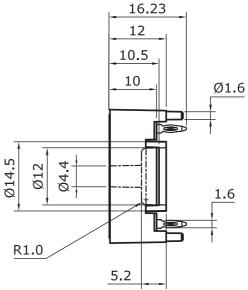
Fig. 5: Gate trigger characteristic

Dimensions: mm

Tolerance system: ISO 2768-m



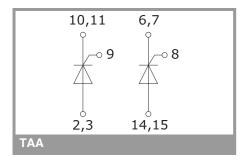




Suggested drilled hole diameter for terminal pins in the circuit board: - refer Mounting Instruction SEMITOP® Classic

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SEMITOP 2 Press-Fit



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

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